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RECEPTION OK

TX/RX NO	7616
CONNECTION TEL	908 771 6159
CONNECTION ID	
START TIME	08/16(FR)19:34
USAGE TIME	06'22"
PGS.	18
RESULT	OK

SN 09/583,599

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE****In re patent application of:** Wang et al.**Serial No.:** 09/583,599**Group Art Unit:** 1741**Filed:** May 31, 2000**Examiner:** Tran, T.**Attorney Docket:** 99A209**Title:** Improved Acid Copper Electroplating SolutionsASSISTANT COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

S I R:

**PETITION TO REVIVE AND  
RESPONSE TO OFFICE ACTION**

In response to the Notice of Abandonment of April 9, 2002, Applicants hereby submit a Petition to Revive the above-referenced application, which was unintentionally abandoned. In support of the requested petition, Applicants submit the following amendment and remarks in response to the Office Action dated September 26, 2001 (Paper No. 6).

**In the claims**

Please cancel claims 9-10, 12, 15, 26-27, 29, 32, 47-48, 50 and 53.

Please amend claims 1, 6, 11, 13-14, 21, 23, 28, 30, 31, 39, 49 and 51-52 as follows:

1. (Amended) An acid copper electroplating composition comprising an aqueous solution of an acid and a copper salt, the improvement comprising the addition of at least one of a carrier compound; a water-soluble, mercapto-containing organic brightener compound; and a leveler compound which comprises an organic compound containing single or multiply positively charged centers; wherein said organic compound is selected from the group consisting of polyethylenimine, 80% ethoxylated; poly(allylamine); poly(allylamine hydrochloride); polyaniline, sulfonated, 5 wt. % in water, 75 mole % sulfonated; poly[bis(2-chloroethyl)ether-alt-